



Inventor: Jeromy M. Eldridge

Title: Perovskite-Type Material Forming Methods, Capacitor Dielectric Forming
Methods, and Capacitor Constructions

Assignee: Micron Technology, Inc.

Docket No.: MI22-2395

INFORMATION DISCLOSURE STATEMENT

PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

The attached form PTO-1449 is submitted in compliance with 37 CFR § 1.56. Copies of the cited art are included with the exception of U.S. patents and published U.S. applications (1273 Off. Gaz. Pat. Off. 55, 05 August 2003). No admission is made regarding whether all the submitted references are prior art.

Citation of these references is respectfully requested.

Respectfully submitted,

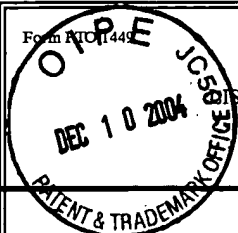
Dated: 10 Dec 2004

By: James E. Lake
James E. Lake
Reg. No. 44,854

12/15/2004 WABDEL R1 00000051 230925 10686333

01 FC:1806

180.00 0P

		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2395		SERIAL NO. 10/686,333	
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					
		APPLICANT Jerome M. Eldridge				ILING DATE October 14, 2003	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	6,403,441	06/02	Takehiro et al			
	AB	5,953,619	09/99	Miyazawa			
	AC	6,730,575	05/04	Eldridge			
	AD	6,169,688	01/01	Noguchi			
	AE	6,524,651	02/03	Gan et al			
	AF	6,194,753	02/01	Seon et al			
	AG	6,258,608	07/01	Jung			
	AH	6,444,592	09/02	Ballantine			
	AI	6,461,931	10/02	Eldridge			
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes No
	AJ	EP 0727832 A1	08/96	EPO/Miyashita et al			
	AK						
	AL						
	AM						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AN						
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
EXAMINER				DATE CONSIDERED			
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							

EV372468431